



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: N. FUKUTOMI, et al.

Serial No: 10/705,706

Filed: NOVEMBER 10, 2003

Title: FABRICATION PROCESS OF SEMICONDUCTOR PACKAGE
AND SEMICONDUCTOR PACKAGE

Group AU: 2813

Examiner: Laura M. Schillinger

Confirm. No: 5226

Allowed: SEPTEMBER 19, 2006

AMENDMENT UNDER 37 CFR 1.312

Mail Stop: ISSUE FEE

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

December 12, 2006

Sir:

Please amend the above-identified application, subsequent to issuance of the Notice of Allowance and Fee(s) Due mailed September 19, 2006, and prior to payment of the Issue Fee, as listed in the following, and as set forth on the following pages:

AMENDMENTS TO THE CLAIMS; and

REMARKS are included following the amendments.